

Typical Properties of Materials					
	Tungsten	Molybdenum	Tantalum	Alumina	Mullite
<b>General</b>					
Atomic Number	74	42	73	6	10
Atomic Weight	183.86	95.95	180.95	0	0
Atomic Volume	9.53	9.41	10.9	0	0
Lattice Type	Body Centered Cube	Body Centered Cube	Body Centered Cube		
Lattice Constant at 20°C [Å]	3.1585	3.1468	3.3026		
Isotope (Natural)	180, 182, 183, 184, 186	92, 94, 95, 96, 97, 98, 100	181		
<b>Mass</b>					
Density at 20°C [gm/cc]	19.3	10.2	16.6	Density [gm/cc], based on ASTM-C20	3.92
Density at 20°C [lb/cu.in.]	0.697	0.368	0.600		2.80
<b>Thermal Properties</b>				<b>Thermal Properties</b>	
Melting Point °C	3410	2610	2996	Thermal Conductivity, 20 °C [Wm degrees K], based on ASTM-C408	30
Boiling Point °C	5530	4830	5430	Coefficient of Thermal Expansion, 25-1000 °C [ $1 \times 10^{-6}/\text{degrees C}$ ] based on ASTM-C372	8.2
Linear Coefficient of Expansion per °C	4.3E-06	4.9E-06	6.5E-06	Specific Heat, 100 °C [J/kg*K] based on ASTM-E1269	880
Thermal Coefficient at 20°C [cal/cm².cm°C/sec]	0.40	0.35	0.130	Maximum Use Temperature [°C], based on No-Load Conditions	1750
Specific Heat at 10°C [cal&g;/°C]	0.032	0.061	0.036	Thermal Shock Resistance, ( $\Delta T_c$ ) [°C] *	200
Working Temperature	1700°C down	1600°C down	Room	*Thermal shock resistance -- Test are run by quenching samples into water from various elevated temperatures. The change in temperature where a sharp decrease in flexural strength is observed is listed as ( $\Delta T_c$ ).	300
Recrystallization Temperature	1300°C - 1500°C	900°C - 1200°C	1050°C - 1500°C		
Stress Relieving Temperature	1200°C	800°C	900°C		
<b>Mechanical Properties</b>				<b>Mechanical Properties</b>	
Tensile Strength at Room Temperature [psi]	100,000 - 500,000	120,000 - 200,000	35,000 - 70,000	Flexural Strength (MOR), 20 °C	375(54)
Tensile Strength, 500°C [psi]	75,000 - 200,000	35,000 - 65,000	25,000 - 45,000	Elastic Modulus, 20 °C [GPa], based on ASTM-F417	370 (54)
Tensile Strength, 1000°C [psi]	50,000 - 75,000	20,000 - 30,000	13,000 - 17,000	Poisson's Ratio, 20 °C, based on ASTM-C848	0.22
Young's Modulus of elasticity [lb/sq. in.]:				Compressive Strength [MPa], based on ASTM-C773	2500 (363)
at Room Temperature	59 x 10E06	46 x 10E06	27 x 10E06	Hardness [GPa(kg/mm²)], based on Knoop 1000 gm	14.1 (1440)
at 500°C	55 x 10E06	41 x 10E06	25 x 10E06	Hardness [GPa(kg/mm²)], based on Rockwell 45 N	83
at 1000°C	50 x 10E06	39 x 10E06	22 x 10E06	Tensile Strength, 25 °C [MPa], based on ACMA Test #4	248 (36)
Poisson's Ratio	0.284	0.321	0.35	Fracture Toughness K(Ic) [Mpa m <sup>1/2</sup> ], based on Notched Beam	4-5
<b>Spectral Emissivity</b>				<b>Electrical Properties</b>	
(Wave Length approx. 0.65μ)	0.45 (900°C)	0.37 (1000°C)	0.46 (900°C)	Dielectric Strength [ac-kV/mm (acV/mil)], based on ASTM-D116	8.7 (220)
Total Emissivity				Dielectric Constant, 1MHz, 25 °C, based on ASTM-D150	9.8
at 1500°C	0.23	0.19	0.21	Dielectric Loss (tan delta), 1MHz, 25 °C, based on ASTM-D2520	0.0001
at 2000°C	0.28	0.24	0.26	Volume Resistivity [ohm-cm], based on ASTM-D1829:	
Nuclear - Cross Section				at 25°C	>10 <sup>14</sup>
Thermal Neutrons [Barns/atom]	19.2	2.4	21.3	at 500°C	2 x 10 <sup>10</sup>
<b>Metallography</b>				at 1000°C	5 x 10 <sup>12</sup>
Etchant	Hot H <sub>2</sub> O <sub>2</sub> 6% Solution	Alk. K <sub>3</sub> Fe(CN) <sub>6</sub> Solution	HF - NH <sub>4</sub> F Solution		
Polishing	Etch and polish repeatedly until grain boundaries appear.				
	Emery to 000 levigated alumina to finish				

